

Reliability data handbook — Universal model for reliability prediction of electronics components, PCBs and equipment

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National foreword

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**Reliability data handbook –
Universal model for reliability prediction
of electronics components, PCBs
and equipment**



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CONTENTS

FOREWORD	5
INTRODUCTION	7
1 Scope	8
2 Normative references	8
3 Terms and definitions	9
4 Conditions of use	10
4.1 Introductory remarks	10
4.2 Assumptions adopted for TR 62380	11
4.3 Influencing factors	13
4.4 How to use the data	14
4.5 Uses and aims of a reliability prediction	15
5 Environment influence	16
5.1 General remarks	16
5.2 Environment types defined	16
5.3 Electrical environment conditions	20
5.4 Validity model according to environment	20
5.5 Components choice	20
5.6 Learning during the deployment phase of new equipment	21
5.7 Mission profile	22
5.8 Mission profile examples	23
6 Equipped printed circuit boards and hybrid circuits (IEC 60326)	25
6.1 Failure rate calculation of an equipped printed circuit board	25
6.2 Hybrid circuits	26
7 Integrated circuits	27
7.1 Validity domain	27
7.2 Junction temperature evaluation of an integrated circuit	27
7.3 The reliability model	30
8 Diodes and thyristors, transistors, optocouplers (IEC 60747-xx)	36
8.1 Evaluating the junction temperature of diodes and transistors	36
8.2 Low power diodes	38
8.3 Power diodes	40
8.4 Low power transistors	42
8.5 Power transistors	44
8.6 Optocouplers	46
9 Optoelectronics	49
9.1 Light emitting diodes diode modules (IEC 60747-12-2, IEC 62007)	49
9.2 Laser diodes modules - Failure rate	52
9.3 Photodiodes and receiver modules for telecommunications (IEC 60747-12)	53
9.4 Passive optic components	54
9.5 Miscellaneous optic components	54
10 Capacitors and thermistors (ntc)	55
10.1 Fixed plastic, paper, dielectric capacitors - Radio interference suppression capacitors (plastic, paper)	55

10.2	Fixed ceramic dielectric capacitors – Defined temperature coefficient – Class I (IEC 60384)	56
10.3	Fixed ceramic dielectric capacitors – Non defined temperature coefficient – Class II – Radio interference suppression capacitors (Ceramic, class II)	57
10.4	Tantalum capacitors, solid electrolyte (IEC 60384)	58
10.5	Aluminum, non-solid electrolyte capacitors - Life expectancy	59
10.6	Aluminum electrolytic capacitor, solid electrolyte	61
10.7	Aluminum electrolytic capacitor, polymer electrolyte (IEC 60384)	62
10.8	Variable ceramic capacitors, disks (Dielectric ceramic) (IEC 60384)	63
10.9	Thermistors with negative temperature coefficient (NTC) (IEC 60539)	64
11	Resistors and potentiometers (IEC 60115)	65
11.1	Fixed, low dissipation film resistors – High stability (rs), general purpose (rc), “minimelf”	65
11.2	Hot molded carbon composition, fixed resistors (IEC 60115)	66
11.3	Fixed, high dissipation film resistors (IEC 60115)	67
11.4	Low dissipation wirewound resistors (IEC 60115)	68
11.5	High dissipation wirewound resistors (IEC 60115)	69
11.6	Fixed, low dissipation surface mounting resistors and resistive array (IEC 60115)	70
11.7	Non wirewound cermet potentiometer (one or several turn) (IEC 60393)	71
12	Inductors and transformers (IEC 61248)	73
13	Microwave passive components, piezoelectric components and surface acoustic wave filters (IEC 61261, IEC 61019, IEC 60368)	74
13.1	Microwave passive components	74
13.2	Piezoelectric components	74
13.3	Surface acoustic wave filters	74
14	Relays	75
14.1	Evaluating voltage and current (vt, it) in transient conditions	75
14.2	Mercury wetted reed relays, low power (IEC 60255)	78
14.3	Dry reed relays (IEC 60255)	80
14.4	Electromechanical relays, miniature or card – European type, thermal relays (power up to 500 W) (IEC 60255)	82
14.5	Industrial relays, high voltage vacuum relays, power mercury wetted relays (IEC 60255)	84
15	Switches and keyboards (IEC 60948)	86
16	Connectors	87
16.1	Circular, rectangular	87
16.2	Coaxial connectors	87
16.3	Connectors for PCBs and related sockets	87
17	Displays, solid state lamps	88
17.1	Displays (IEC 61747)	88
17.2	Solid state lamps (IEC 60747)	88
18	Protection devices (IEC 60099, IEC 60269, IEC 60738, IEC 61051)	89
18.1	Thermistors (PTC)	89
18.2	Varistors	89
18.3	Fuses	89
18.4	Arrestors	89
19	Energy devices, thermal management devices, disk drive	90
19.1	Primary batteries	90
19.2	Secondary batteries	90

19.3 Fans	90
19.4 Thermoelectric coolers	90
19.5 Disk drive	90
19.6 Converters (IEC 60146).....	90
Table 1 – Mission profiles for spatial.....	10
Table 2 – Mission profiles for military.....	10
Table 3 – Description and typical applications of the commonest types of environment	17
Table 4 – Mechanical conditions according to the environment: characteristic shocks and vibrations.	18
Table 5 – Mechanically active substances.....	19
Table 6 – Chemically active substances.....	19
Table 7 – Typical conditions for each environment type according to Table 3 (mechanically and chemically active substances and climatic conditions)	19
Table 8 – Table of climates.....	23
Table 9 – Mission profiles for Telecom.....	23
Table 10 – Mission profiles for military and civil avionics	24
Table 11 – Mission profiles for automotive	24
Table 12 – Thermal resistance as a function of package type, the pin number and airflow factor	28
Table 13 – Typical values of the air flow speed V, and the air flow factor K.....	29
Table 14 – Thermal expansion coefficients α_s and α_c	32
Table 15 – Failure distribution (for non interfaces integrated circuits)	32
Table 16 – Values of λ_1 and λ_2 for integrated circuits families	33
Table 17a – λ_3 values for integrated circuits as a function of S (pin number of the package) 34	
Table 17b – λ_3 values for surface mounted integrated circuits packages as a function of D (package diagonal).....	35
Table 18 – Values of λ_B and junction resistances for active discrete components	37
Figure 1 – Time dependant failure rate of a new electronic printed circuit board.....	21
Figure 1 – Time-dependant failure rate of a new electronic printed circuit board	21
Figure 2 – Equivalent diagram representing the circuit of a relay contact	75
Figure 3 – Positions of capacitors in the real circuit diagram for which the values must be counted in C.....	75
Figure 4 – Regions adopted for the purposes of Figures 5, 6 and 7	76
Figure 5 – Evaluating the ratios V_t/V and I_t/I according to $R=R_1+R_2$, C, L, and C_p , L_p (R in k Ω , C, C_p in nF ; L , L_p in mH).....	76
Figure 6 – Evaluating ratios V_t/V and I_t/I when L and C are not known	77
Figure 7 – Default values of V_t/V and I_t/I when nothing is known about the electrical circuit of the contact.....	77

INTERNATIONAL ELECTROTECHNICAL COMMISSION

RELIABILITY DATA HANDBOOK – UNIVERSAL MODEL FOR RELIABILITY PREDICTION OF ELECTRONICS COMPONENTS, PCBs AND EQUIPMENT

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The text of this standard is based on the following documents:

Enquiry draft	Report on voting
47/1705/DTR	47/1722A/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This reliability calculation guide for electronic and optical card, is an important progress compared to older guides. Calculation models take directly into account the influence of the environment. The thermal cycling seen by cards, function of mission profiles undergone by the equipment, replace environment factor which is difficult to evaluate. These models can handle permanent working, on/off cycling and dormant applications. On the other hand, failure rate related to the component soldering, is henceforth-included in component failure rate.

RELIABILITY DATA HANDBOOK – UNIVERSAL MODEL FOR RELIABILITY PREDICTION OF ELECTRONICS COMPONENTS, PCBs AND EQUIPMENT

1 Scope

This technical report provides elements to calculate failure rate of mounted electronic components. It makes equipment reliability optimization studies easier to carry out, thanks to the introduction of influence factors.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60086 (all parts), *Primary batteries*

IEC 60099 (all parts), *Surge arresters*

IEC 60115 (all parts), *Fixed arrestors for use in electronic equipment*

IEC 60146, (all parts), *Semiconductor convertors – General requirements and line commutated convertors*

IEC 60255 ((all parts), *Electrical relays*

IEC 60269 (all parts), *Low-voltage fuses*

IEC 61951 (all parts), *Secondary cells and batteries containing alkaline or other non-alkaline electrolytes – Portable sealed rechargeable single cells*

IEC 60326 (all parts), *Printed boards*

IEC 60368 (all parts), *Piezoelectric filters of assessed quality*

IEC 60384 (all parts), *Fixed capacitors for use in electronic equipment*

IEC 60393 (all parts), *Potentiometers for use in electronic equipment*

IEC 60535, *Jet fans and regulators*

IEC 60539 (all parts), *Directly heated negative temperature coefficient thermistors*

IEC 60721-3 (all Parts 3), *Classification of environmental conditions – Part 3: Classification of groups of environmental parameters and their severities*

IEC 60738 (all parts), *Thermistors - Directly heated positive step-function temperature coefficient*

IEC 60747 (all parts) *Semiconductor devices - Discrete devices*

IEC 60747-12 (all Parts 12) *Semiconductor devices - Part 12: Optoelectronic devices*

IEC 60747-12-2, *Semiconductor devices – Part 12: Optoelectronic devices – Section 2: Blank detail specification for laser diode modules with pigtail for fibre optic systems and sub-systems*

IEC 60748 (all parts) *Semiconductor devices – Integrated circuits*

IEC 60879, *Performance and construction of electric circulating fans and regulators*

IEC 60948, *Numeric keyboard for home electronic systems (HES)*

IEC 61019 (all parts), *Surface acoustic wave (SAW) resonators*

IEC 61051 (all parts), *Varistors for use in electronic equipment*

IEC 61248 (all parts), *Transformers and inductors for use in electronic and telecommunication equipment*

IEC 61747 (all parts), *Liquid crystal and solid-state display devices*

IEC 61261 (all parts), *Piezoelectric ceramic filters for use in electronic equipment – A specification in the IEC quality assessment system for electronic components (IECQ)*

IEC 61951 (all parts), *Secondary cells and batteries containing alkaline or other non-acid electrolytes*

IEC 61951-1, *Secondary cells and batteries containing alkaline or other non-acid electrolytes – Portable sealed rechargeable single cells*

IEC 61951-2, *Secondary cells and batteries containing alkaline or other non-acid electrolytes – Nickel-metal hydride*

IEC 62007 (all parts), *Semiconductor optoelectronic devices for fibre optic system applications*

IEC 62255 (all parts), *Multicore and symmetrical pair/quad cables for broadband digital communications (high bit rate digital access telecommunication networks) - Outside plant cables*

ETS 300 019, *Environmental engineering (EE); Environmental conditions and environmental tests for telecommunications equipment*

ISO 9000:2000, *Quality management systems – Fundamentals and vocabulary*

UTE C 96-024:1990, *Modèles thermiques simplifiés des circuits intégrés monolithiques*

3 Terms and definitions

For the purposes of this technical report, the following definitions apply.

3.1

spatial

Mission profiles corresponding to the MIL-HDBK-217F "Space; flight" environment.

NOTE Only one working phase is taken into account during each orbital revolution (LEO), or earth revolution (GEO).

Table 1 – Mission profiles for spatial

Application types	$(t_{ac})_1$ °C	τ_1	τ_{on}	τ_{off}	n_1 cycles/year	ΔT_1 °C/orbit
Low earth orbit (LEO) with On/Off cycling	40	0,15	0,15	0,85	5256	$\frac{\Delta T_{jc}}{3} + 7$
Low earth orbit (LEO) permanent working	40	1	1	0	5256	3
Geostationary earth orbit (GEO) permanent working	40	1	1	0	365	8

3.2 military

Mission profiles corresponding to the MIL-HDBK-217F "Ground; mobile" environment.

NOTE Two working phases are taken into account:

Phase 1: 36 annual switch on

Phase 2: 365 days of dormant mode

Table 2 – Mission profiles for military

Application type	$(t_{ac})_1$ °C	τ_1	τ_{on}	τ_{off}	n_1 cycles/year	ΔT_1 °C/cycle	n_2 cycles/year	ΔT_2 °C/cycle
Portable Radio	26	0,01	0,01	0,99	36	$\frac{\Delta T_j}{3} + 15$	365	8

4 Conditions of use

4.1 Introductory remarks

4.1.1 Theory of reliability predictions

Calculation of a reliability prediction for non-redundant equipment is the very first step in any complete reliability study concerning that equipment, and indeed, of any study of the reliability, availability, or safety of a system.

Reliability predictions are based on numerous assumptions, all of which need to be verified (choice of component family, for example).

A reliability study of an item entails not only verifying these assumptions, but also optimizing its reliability (qualification of components and mounting processes, minimizing risk of external failure, etc).

A reliability prediction is essential, but no more so than research into the best possible reliability for least cost.

This handbook provides all the information needed to calculate electronic component and equipped printed circuit board failure rates: failures rates delivered include the influence of component mouting processes.

4.1.2 Structure of the handbook

The handbook is specifically designed as an aid to research into how to maximize equipment reliability, and to assist in the design of the equipment, by introducing various influencing factors (see also 4.3). In order to meet this objective, it is important that any reliability prediction should begin with the start of design (and then be finalised in accordance with 4.5.4). Similarly, the choice of values for the influencing factors should not be automatic.

4.1.3 Data source

The reliability data contained in the handbook is taken mainly from field data concerning electronic equipment operating in four kinds of environment:

- a) «Ground; stationary; weather protected» (in other words: equipment for stationary_use on the ground in weather protected locations, operating permanently or otherwise).

This applies mainly to telecommunications equipment and computer hardware.

- b) «Ground; stationary; non weather protected» (in other words: equipment for stationary_use on the ground in non-weather protected locations).

This relates mainly to public payphones and GSM relays.

- c) «Airborne, Inhabited, Cargo» (in other words: equipment used in a plane, benign conditions).

This relates to on board calculators civilian planes.

- d) «Ground; non stationary; moderate» (in other words: equipment for non-stationary use on the ground in moderate conditions of use).

This concerns mainly on board automotive calculators and military mobile radio.

By processing the raw data (statistical processes, results based on geographic distribution, according to equipment type, etc.), it has been possible to include various influencing factors and eliminate the main aberrant values. Other influencing factors are derived from the experience of experts (failure analyses, construction analyses, results of endurance tests).

The values adopted are those considered most probable at the present time (1992-2001).

This databook does not give any part count values, because mission profiles are needed in order to have credible values.

4.2 Assumptions adopted for TR 62380

4.2.1 Nature of data

4.2.1.1 Reliability data

The reliability data in this handbook comprises failure rates and, for some (very few) component families, life expectancy.

Failure rates are assumed to be constant either for an unlimited period of operation (general case) or for limited periods: in these particular cases the laws governing failure rates versus time have not been adopted in the interests of simplicity.

Apart from a few exceptions (see section 4.2.1.3), the wear-out period is never reached by electronic components; in the same way it is accepted, again apart from some exceptions (see section 4.2.1.2), that the added risks of failure during the first few months of operation can be disregarded.

4.2.1.2 The infant mortality period

In practice, except for a few component families, the increased risk of failure during the first months of operation can be disregarded, because of the diversity of reasons for variations or uncertainty in the failure rate. This superficially simplistic hypothesis is in fact very realistic. It is confirmed by field data concerning the operation of equipment designed very carefully, with well chosen components (based on compatibility with use) and produced by a well controlled production system, as is generally the case for the components covered by this handbook.

4.2.1.3 Wear-out period

For the vast majority of components, the -wear-out period (during which failures take on a systematic character) is far removed from the periods of use (which range from 3 to 20 years).

There are, however, two cases in which the occurrence of wear-out failures should be taken into account (the failure rate of which increases with time):

- a) For some families, if due care is not taken, the wear-out mechanisms may give rise to systematic failures after too short a period of time; metallization electromigration in active components, for example.

This risk needs to be eliminated by a good product design, and it is important to ensure this by qualification testing. In other words, it should not be taken into account for a prediction, and should be eliminated by qualification testing and by technical evaluation, which are, therefore, of critical importance.

- b) For some (few) component families, the wear-out period is relatively short. For these families, this handbook explains how to express the period for which the failure rate can be considered constant. This life expectancy is subject to influencing factors.

Such families include relays, aluminium capacitors (with non-solid electrolyte), laser diodes, optocouplers, power transistors in cyclic operation, connectors and switches and keyboards.

For these component families, it is important to ensure that the life expectancy given by the handbook is consistent with the intended use. If not, room for manoeuvring is fairly restricted: you can reduce the stresses, change the component family (or sub-family: for aluminium capacitors with non-solid electrolyte, there are several types characterized by different qualification tests).

Provision can also be made for preventive maintenance.

NOTE: As before, and in the interests of simplicity, this handbook does not give the wear-out failure mathematical model (for which the failure rate increases over time), but a period during which the rate can be considered constant (in some cases the period at 10% of the cumulative failure rate).

4.2.2 Nature of failures

4.2.2.1 Intrinsic failures

The data in this handbook covers intrinsic failures (apart from the few exceptions given in 4.2.2.2).

In practice (see section 4.1.3), the raw reliability data has been processed to eliminate non-intrinsic component failures.

4.2.2.2 Special case of non-intrinsic residual failures due to electrical overloads

There is, necessarily, a small proportion of non-intrinsic failures in the data, because it is impossible to detect all the non-intrinsic failures when they are residual.

Take, for example, the reliability of the components used in equipment located “at the heart” of a system, which is significantly better than that of the components located at the periphery (in other words connected to the external environment). It is understood that this is due to residual overloads, since the equipment is assumed adequately protected.

For the purpose of this handbook, we have therefore included an utilisation factor to take into account nonintrinsic residual failures due to the electrical environment for active components.

4.2.2.3 Other non-intrinsic failures

The other non-intrinsic failures (due to errors of design, choice, uses) are excluded from this handbook.

Errors of this kind should be avoided; hence they are not taken into for predictions. As a matter of fact, they are very largely independent of component family.

However, for some particular objectives, such as calculation of stocks of spare parts, it may be useful to include the risks of non-intrinsic residual failures due to design errors: some indications are given in section 4.4.3.

4.2.3 Large-scale integrated circuit, production date influence

Since the 90's, the reliability growth of components no longer occur, as in the 70's and the 80's; thanks to fields failures returns data collections. This is particularly true for integrated circuits, and can be attributed to: generalization of nitride based passivations, generalization of dry etching and better planarization controls. However, the integration density for integrated circuits continues to grow at the same rate as in the past, at a constant reliability figure. For this reason, and in order to takes into account the Moore law, it is necessary to know the manufacturing year to calculate the failure rate of integrated circuits.

4.3 Influencing factors

4.3.1 Component failure rate

The component failure rate depends on a number of operational and environmental factors. This is why, for each component family, the handbook gives a base failure rate value (normally a value which corresponds to the commonest internal temperature taken as a reference) multiplied by a number of influencing factors. This simplified, empirical expression takes account of the more significant influencing factors when it comes to conditions of use.

The main factors adopted are as follows:

a) Factors giving the influence of temperature (π_t , π_w)

It is now widely accepted that temperature has a moderate effect on component reliability. The effect is significant for some families (active components and aluminum capacitors with non-solid electrolyte). The models adopted are those which give the effect of temperature on the predominating failure mechanisms (which are not normally the "wear-out" mechanisms).

For semiconductors, an Arrhenius equation has been applied with activation energy of 0.3 to 0.4 electron volts.

For passive components, an Arrhenius equation has been applied with an activation energy of 0.15 to 0.4 electron volts.

Factor π_w for potentiometers gives the influence of load resistance on the temperature rise.

In the case of power dissipating components, the thermal resistance (semiconductors) or the equation giving the internal temperature as a function of ambient temperature (resistors) has been given.

b) Factors giving the influence of special stresses:

Utilization factor π_u for thyristors, Zener diodes (operating permanently powered or otherwise).

Factor π_A for Aluminum liquid electrolyte capacitors giving the effect of current pulses.

Factor π_Y for relays (operating cycle rate).

Factor π_i for connectors (current intensity).

c) Factors giving the influence of applied voltage (π_s).

The influence of applied voltage is taken into account for transistors and optocouplers (voltage applied between input and output).

4.3.2 Life expectancy

Life expectancy, when limited, is also influenced by certain factors (optocoupler operating current; temperature of aluminum capacitors with non-solid electrolyte; contact current for relays).

Life expectancy can be expressed as a number of cycles (power transistors, switches).

4.4 How to use the data

4.4.1 Calculation method

Given that the component failure rates are assumed constant, the failure rate of a non-redundant equipment can be obtained by adding together the failure rates of its individual components. In this handbook, the failure rates given for components include the effects of the mounting on a printed circuit board, the failure rate of the naked PCB or hybrid has to be added.

Clause 6 of this handbook explains the method to be used to calculate the failure rate of a printed circuit board or a hybrid.

4.4.2 Reliability prediction results

The results of a reliability prediction are many and various, and not limited to failure rate: the following information is also obtained:

- Failure rate (of component or equipment).
- Choice of technical construction for some components (choice of component family).
- Choice of conditions of use.

4.4.3 Failure rate

The failure rate can be used directly if the aim is to identify a reference base. Such is the case for many objectives described in 4.5.

However, if the aim is to obtain an accurate estimate of stocks of spare parts, the result should be updated to take account of non-intrinsic failures:

- unconfirmed failure phenomena (equipment, subsystem, identified as defective and found to be OK on repair);
- incorrect component usage, wrong choice of components for the first months of use of equipment of new design (period of improving reliability);
- incorrect maintenance, inappropriate use, human error, environmental attack;
- production process learning factor (component mounting process, etc).

The appropriate uprating factors cannot be given in this handbook: they depend on the prior experience of a company and how new the equipment production process is (for example, for unconfirmed failures, the uprating factor ranges from 10% to over 100%, depending on newness).

4.4.4 In cases where conditions are not yet known default conditions can be assumed.

According to 4.5.1, reliability prediction calculations should begin as early as possible, at the start of the equipment design phase, even if not all the applicable conditions can yet be known: in this case default values can be used provisionally, to help determine those conditions which are as yet unknown. These default values will then be gradually discarded as the definitive conditions are identified.

This method is far preferable to the simplified calculation method (for which all the values are replaced by default values, including those, which are already known).

The calculations must therefore be prepared in such a way as to enable values to be modified easily.

4.5 Uses and aims of a reliability prediction

4.5.1 Reliability prediction as an aid to equipment design

The most beneficial use of a reliability prediction is as an aid to equipment designers. In this case, the help is based on determination of the stresses and factors influencing the reliability of each component (temperature, input voltage, technical construction of the components, etc.). Predictions based on this handbook will lead the originators of a new design to choose the best conditions and the best component families, and to draw up component qualification or evaluation programmes.

If this important objective is to be met, it is essential for the reliability prediction to be begun at the very start of design, by the design originators, and then revised as required. The work should be carried out in close collaboration with the company's component quality experts.

4.5.2 Reliability prediction to assess the potential of new equipment

The predicted reliability can be compared with the reliability objectives or stated requirements.

4.5.3 Predicted reliability values as a basis for contractual reliability values

The contractual value of a failure rate must be determined on the basis of the predicted value; these two values will not necessarily be equal: a number of contractual values may be assumed depending on observation period or certain data may be modified provided it is justified. However, in all cases, the predicted value should be taken as the base.

4.5.4 Where used in conjunction with other characteristics of a project (electrical characteristics, weight, etc.), the results of a reliability prediction can be used to compare different project solutions, such as when evaluating proposals from tenderers. Comparisons of this kind are possible only if the data used is the same, hence the existence of a reliability data handbook.

4.5.5 The predicted failure rates for the individual items of a system are crucial when calculating system dependability and reparability.

4.5.6 Reliability predictions can be used as a basis for evaluating stocks of equipment and spare components required for maintenance (however, in this case, it is important to take account of probable non-intrinsic failures, as was explained in 4.4.3). The purpose of a study of this kind is to optimize stocks of spare parts (avoid stock outages, but also avoid excessive and costly stocking levels).

4.5.7 Reliability predictions can be used as a benchmark for assessing results observed in operation. Indeed, observed results cannot be assessed effectively without a benchmark: mediocre reliability would be considered normal and there would be no attempt at improvement.

Obviously we should not expect observations to mirror exactly the predicted reliability values, for a number of reasons:

- Predictions are based only on intrinsic reliability; they do not therefore take account of external overload conditions (however, according to 4.2.2, they do take account of residual overloads).
- Predictions do not take account of design errors or incorrect use of components.
- Predictions do not take account of the risks involved in using lots of components with poor reliability.

These departures from reality, far from being a handicap are in fact an advantage; in practice, the differences can be used to reveal a lack of reliability and, following analysis, take corrective action. This very important quality enhancement process is crucial when it comes to minimizing the infant mortality period and correcting equipment design errors.

5 Environment influence

5.1 General remarks

Experience has shown that component reliability is heavily influenced by mechanical and climatic environment conditions, as well as by electrical environment conditions (residual overload).

This factor is therefore included in this handbook, based on observations and published values; for simplicity, climatic and mechanical environment conditions have been classified in ten or so environment types. However, the mission profile has to be taken into account (see 5.7), to determine estimated failure rate of components in the considered environment.

5.2 Environment types defined

The environment types are based on IEC 60721-3 («classification of groups of environmental parameters and their severity»), with some simplifications, and the specification ETS 300 019 (ETSI specification: environmental conditions for telecommunications equipment).

Table 3 gives, for the various types of environment adopted for the purposes of this handbook, the following information:

- the short form designation adopted for this handbook;
- the complete designation (generally according to IEC 60721-3);
- the main stresses included;
- some typical applications.

Table 4 quantifies the mechanical stresses (shock and vibration) for the main types of environment.

Tables 5 define the environmental conditions according to the presence and activity of chemical and mechanical substances (definitions given in table 7 based on the conventions summarized in Tables 5 and 6), and according to climatic conditions.

Table 3 – Description and typical applications of the commonest types of environment

Environment description			Description of the environment	Applications
Short form designation (adopted in the handbook)	Complete designation			
Ground; stationary; weather protected	Equipment for <u>stationary</u> use on the <u>ground</u> in Weather protected locations		Controlled temperature and humidity, low stress good maintenance	Equipment in environmentally controlled premises
Ground; stationary non weather protected	Equipment for stationary use on the ground; in non Weather protected locations		Some mechanical and climatic stresses (moderate) Average quality maintenance	Equipment located in premises with little or no environmental control: - phone booths - equipment in public buildings - equipment in streets, stations, etc, - equipment in industrial environments.
	important note: the phrase "non weather protected" (according to IEC 60721-3) applies to the equipment and not to the components. With regard to, the components (which are protected from the elements), the main difference from the type "ground; fixed; protected" lies in the absence of environmental control (humidity and temperature).			
Ground; non stationary; benign	Equipment for <u>non-stationary</u> use on the <u>ground</u> , in <u>benign</u> conditions		Mechanical stress is more severe than for "ground; stationary; non Weather protected" Sometimes difficult maintenance	Radiotelephones - Portable equipment on ground vehicles. Railway rolling Stock equipment
Ground; non stationary; severe	Equipment for <u>non-stationary</u> use on the <u>ground</u> , in <u>severe</u> conditions		As for "ground; non stationary benign", but with more severe; mechanical stresses	
Satellite; flight	Used on board an orbiting satellite		Very low mechanical stresses	
Satellite; launch	Used on board a satellite During launch		Extremely severe shock High amplitude vibration and high frequencies (up to 2 000 Hz)	
Airborne; benign	Used in an aircraft in ...	benign conditions	Conditions similar to those of "ground; non-stationary; benign-", but with more intense vibration up to 2 000 Hz	Other applications (other than "aircraft" and "ship") are possible, rovided that the stresses are comparable.
Airborne; moderate		moderate conditions	The qualifying terms "moderate", "severe" and "extremely severe", are defined in table 2; they represent increasing levels of mechanical stresses.	
Airborne; severe		severe conditions		
Airborne; extremely severe		extremely severe conditions		
Naval; benign	Used on board a ship in ...	benign conditions	Conditions similar to those of “ground; stationary; non-weather protected”, but with more pronounced shock and vibration. The qualifying terms, "benign" and “severe” represent the mechanical stresses according to table 2.	
Naval; severe		severe conditions		

Table 4 – Mechanical conditions according to the environment: characteristic shocks and vibrations.

VIBRATIONS											SHOCKS	
Accelerations	Frequencies										peak acceleration	Duration
m/s ²	Some Hz up to the above frequency. (Hz)	50	100	200	200	300	300	500	1000	2000	m/s ²	ms
↓	↓	22	11	6	11	6	11	2,3	6	0,5	←	←
1	200	Ground stationary Weather-protected										
10	200			Ground stationary Non weather protected								
20	200		← Naval ; benign →									
20	500		← Ground ; non stationary ; benign →									
20	2000		Airborne ; benign									
30	500						← Ground; non stationary; severe →					
30	2000		Airborne; moderate									
50	200		← Naval severe →									
80	2000				Airborne; severe							
150	2000				Airborne; extremely severe						Satellite launch	

Tables 5 and 6: Represent the definition of concentration classes used in Table 7 for active substances

Table 5 – Mechanically active substances

Designation of classes used in Table 7	Sand (Mg/M3)	Dust		Examples of type of environment
		(Mg/M3)	(Mg/M2 h)	
Negligible	0	0,01	0,4	Naval; benign
Low	30	0,2	1,5	Ground; weather protected
Moderate	300	0,4	1,5	Ground; non weather protected
High	3000	4	40	Ground; non stationary; severe

Table 6 – Chemically active substances

Designation of classes used in Table 7	Salt mist	S0 ₂	H ₂ S	Cl	N0 ₂	Examples of type of environment
		(proportion in 10 ⁻⁹)				
Low	(low)*	30	7	7	50	Ground; weather protected
Moderate	(moderate)*	100	70	70	300	Ground; non weather protected
High	(high)*	400	400	70	500	Naval; severe

* No figure has been published

* No figure has been published

Table 7 – Typical conditions for each environment type according to Table 3 (mechanically and chemically active substances and climatic conditions)

	Active substances concentration (classes according to Tables 5 and 6)			Relative humidity %	Mean temperature °C	Rapid changes of Temperature: qualitative estimation of temperature range
	Mechanically active substances	Chemically active substances				
		Gaseous substances	Fluid substances			
		Concentration class 3ccording to Table 5	Concentration class according to Table 6			
Ground; stationary; weather protected	low	low	negligible	40 to 70	+5 to +45	negligible
Ground; stationary; non weather protected	moderate	moderate	negligible	5 to 100	-40 to +45	low
Ground; non stationary; benign	moderate	moderate	negligible	5 to 100*	-40 to +45	low
Airborne; benign	low	low	negligible	510 100	-40 to +45	low
Airborne; moderate	low	low	negligible	5 to 100	-40 to +45	low
Naval; benign	very low	low	negligible	5 to 100	-40 to +45	low
Ground; non stationary; severe	high	moderate	low	5 to 100	-40 to +70	moderate
Airborne; severe	high	moderate	high	5to-100	-65 to +85	high
Naval; severe	moderate	high	high	10 to 100	-40 to +70	high
Airborne; extremely severe	high	moderate	high	5 to 100	-65 to +85	high
Satellite; launch	low	moderate	low	0 to 50	-40 to +20	high
Satellite ; Orbit	very low	moderate	low	0	-40 à +65	moderate

* 40 to 70 on board trains (railway equipment)

* 40 to 70 on board trains (railway equipment)

5.3 Electrical environment conditions

Reliability is also heavily dependent on electrical environment conditions (voltage and current overloads). This applies in particular to a component connected to interface circuits between an electronic circuit board and the outside environment (another equipment, especially if remotely located).

First priority is to protect the exposed components appropriately (by a system of protection comprising components designed to resist overload conditions). However, it is often found that the reliability of exposed and protected components does not match that of components located "at the heart" of an equipment. Electrical environment conditions for the active components have therefore been included (bearing in mind that the effect of residual overloads after a protection system is of concern).

The influence of the electrical environment for other families (some passive components), might equally be applied.

5.4 Validity model according to environment

Failures analysis undertaken on field failed active devices, during the period 1992 to 2001, have shown that:

- For the "ground; stationary; weather protected" environment, there is no package related defects, and nothing coming from the mounting process.
- For "ground; stationary; non-weather protected", "ground non-stationary; severe" and "airborne benign" environments, the main observed defects are caused by thermomechanical constraints applied to components mounted on PCBs. The failure rate related to the humidity is insignificant (for active components, especially since the generalization of the nitride based passivations). Furthermore, in these studied environments no defect related to mechanical shocks or to vibrations to chemical contamination has been observed. Consequently, these failure mechanisms have not been taken into account in the models.

Therefore, to use these models correctly, it is necessary to make appropriate qualification tests to verify these hypotheses for the considered environment. Plastic encapsulated devices are, in most of the described environments in this report, insensitive to shock and vibration.

Furthermore, for the "ground; stationary; non weather protected", it is necessary to ensure that there is no condensation on cold parts of the equipment (especially for equipment having a standby mode), and also there is no streaming on the equipment itself, this, to avoid any corrosion phenomenon.

5.5 Components choice

It is the responsibility of the manufacturer to guarantee the life duration specified by the final user and that components used in equipment are compatible with the environment. Therefore, premature usury phenomena shall not occur, during the useful life period of the equipment in normal utilization conditions prescribed by the final user (see 4.2.1.3).

However some components may have limited life duration, but a preventive maintenance has to be nevertheless indicated to the final user (see 4.2.1.3).

It is the responsibility of the component manufacturer to provide qualification and evaluation results of degradation mechanisms to the manufacturer and to insure that the appearance of usury mechanisms will be postponed beyond the useful life period of the equipment in normal utilization conditions, as prescribed by the final user.

Consequently, the equipment manufacturer has to choose components manufacturers who have the best "commercial practice" concerning quality, those who are ISO 9000 certified, practice the statistical process control and are under qualified manufacture line approval (or able to be).

In these conditions, there are no longer any reasons to take into consideration quality factors, and the infant mortality period related to new component technology is neglected only qualified productions lines and stabilized ones are considered here.

When an equipment manufacturer uses a new component technology, and when such a manufacturer has not been able to justify the life duration in normal use conditions of its device, the equipment manufacturer has to undertake tests allowing justification of the life duration of this component to the final user.

5.6 Learning during the deployment phase of new equipment

Models retained in this report allow for calculation of an electronic card to reach a reliability objective in its stabilised production phase. However, the operational reliability follow up of a newly developed electronic card, function of its deployment in the field, shows that there is a more or less long learning period, according to the improvement of the components implementation on the PCB and the components choice rectification for those having problem in the field (see Figure 1).

Each manufacturer has to calibrate the learning period according to his own experience. However experimentally, on many electronic cards and with several manufacturers, the ratio between the failure rate during the starting period of deployment and the one in the stabilized period, is between 2 and 3.

Consequently, as soon as the observed failure rate (out of non-defective removed cards: NDF) during the beginning of the deployment of an electronic card exceeds three times the estimated calculated value, a corrective action has to be taken.

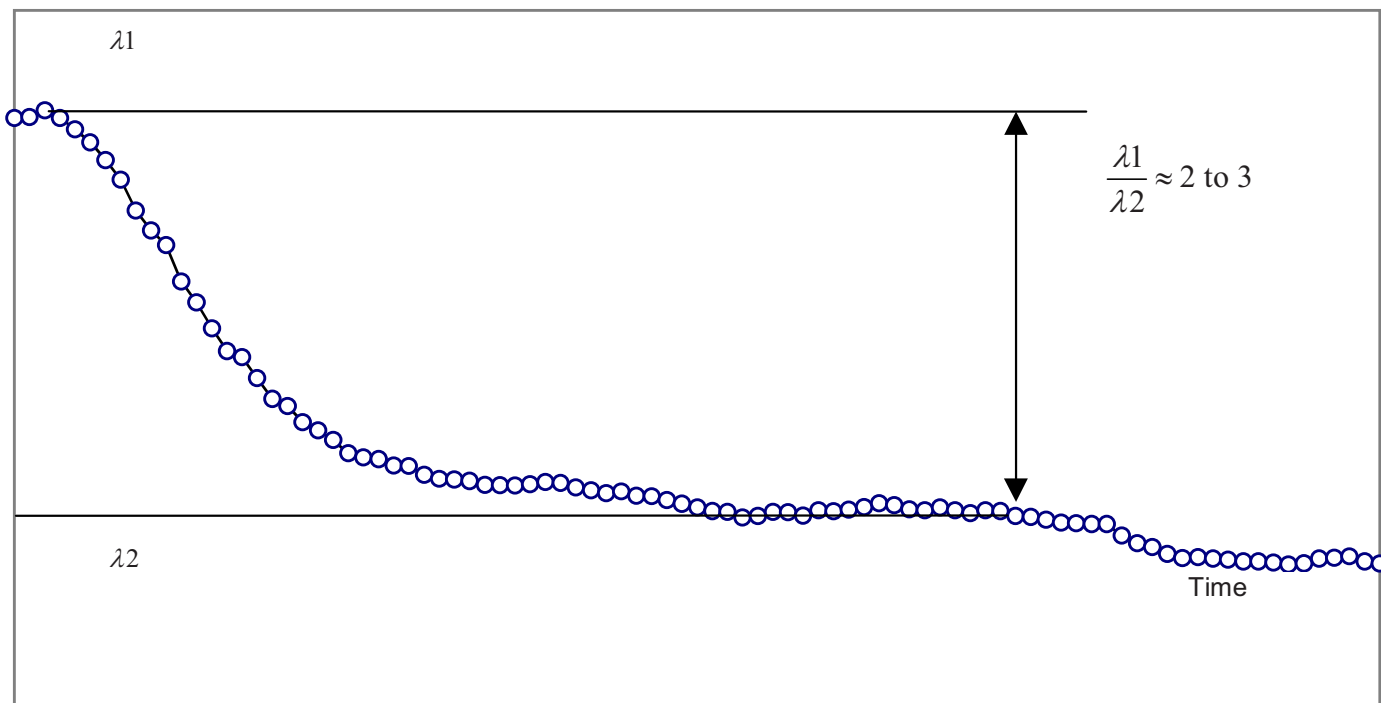


Figure 1 – Time-dependant failure rate of a new electronic printed circuit board

5.7 Mission profile

Estimated reliability calculation of equipment has to be done according to its field use conditions. They are defined by the mission profile.

A mission profile has to be decomposed in several homogeneous working phases, on the basis of a typical year of use. The following phases are to be considered:

- on/off working phases with various average outside temperatures seen by the equipment ;
- permanent-working phases with various average outside temperature swings seen by the equipment ;
- storage or dormant phases mode with various average outside temperature swings seen by the equipment.

For a reliability calculation, the time quantity which has to be taken into account on a field return coming from an equipment population, is therefore, the number of calendar hours of the installed population of this equipment, including working as well as storage or dormant hours.

Parameters necessary to define the mission profile of equipment are the following:

- $(t_{ae})_i$: average outside ambient temperature surrounding the equipment, during the i^{th} phase of the mission profile.
- $(t_{ac})_i$: average ambient temperature of the printed circuit board (PCB) near the components, where the temperature gradient is cancelled (or the one of the component considered as the most critical for reliability, during the i^{th} phase of the mission profile).
- τ_i : annual ratio of times for the PCB, in permanent working mode with supply, and at the $(t_{ac})_i$ temperature.
- τ_{on} : total annual ratio of time for the PCB, in permanent working mode with supply ($\tau_{on} = \sum_{i=1}^y \tau_i$).
- τ_{off} : total annual ratio of time for the PCB, in non working or storage/dormant modes. ($\tau_{on} + \tau_{off} = 1$).
- n_i : annual number of thermal cycles seen by the components of the PCB, corresponding to the i^{th} phase of the mission profile with an average swing ΔT_i .
- ΔT_i : average swing of the thermal variation seen by the components of the PCB, corresponding to the i^{th} phase of the mission profile.

For an on/off phase the following relation exists: $\Delta T_i = \left[\frac{\Delta T_j}{3} + (t_{ac})_i \right] - (t_{ae})_i$

With ΔT_j : increase of the internal temperature of the component as compared to t_{ac} , during a τ_{on} phase. (This is the junction temperature increase for an integrated circuit or a discrete device; this is the surface temperature increase for a passive device.) Only the third of its value has to be taken into account for a ΔT_i calculation, taking into account the fact that thermomechanical stresses induce defects at the solder joint of the components, but also at the wire bounding of the die. The temperature to be taken into account is therefore a compromise on the internal temperature increase of the component. Some thermal simulations have shown that a third of this value is a good compromise.

$(t_{ae})_i$: for the French climate, 11 °C is used for "Ground; stationary; non weather protected" ("ground; fixed" of MIL-HDBK-217F) environment, and 14 °C for the world-wide climate.

$(t_{ac})_i$: is obtained, taking the mean value of the temperature increase observed on the PCB near the components as compared to the external temperature of the equipment, and adding the value of $(t_{ae})_i$ for the considered phase.

t_{ac} = average temperature increase of the PCB near components + t_{ae}

For a storage or permanent working phase: ΔT_i = average of the difference between maximal and minimal temperatures per cycle seen by the equipment on the considered phase. If this value is below 3 °C, the value becomes $\Delta T_i = 0$, taking into account the fact that for these conditions, thermomechanical stresses are thermally independent in the COFFIN-MANSON equation.

For the majority of applications, one day corresponds to one cycle, and ΔT_i corresponds to the annual daily mean of the daylight / night temperature difference seen by the equipment park in the considered climate. For the French climate, $\Delta T_i = 8$ °C. For the world-wide climate, $\Delta T_i = 10$ °C.

A daily temperature variation is always superimposed on a permanent working phase according to the climatical environment of the equipment. For on/off working this daily variation is also applied on the equipment, however, only the greater temperature variation has to be taken into account, because the highest one has the main effect on the reliability of the device packages and on the mounting process.

Table 8 – Table of climates

Climate type	t_{ac} night	t_{ac} day-light	t_{ac} mean day-light/night	ΔT_i day-light/night
World-wide	5 °C	15 °C	14 °C	10 °C
France	6 °C	14 °C	11 °C	8 °C

5.8 Mission profile examples

Mission profiles described here in after are given as examples.

5.8.1 Telecoms

There is only one annual working phase to consider for a permanent working.

Table 9 is given for a permanent working. Values for "ground; stationary; non weather protected"(Ground; fixed for Mil-HDBK-217F) are given for the French climate, but other climates can be calculated.

Table 9 – Mission profiles for Telecom

Environment types	Equipment types	$(t_{ae})_i$ °C	$(t_{ac})_i$ °C	τ_1	τ_{on}	τ_{off}	n_1 cycles/year	ΔT_1 °C/cycle
Ground; benign: (G_B)	switching	20	30	1	1	0	365	0
Ground; benign: (G_B)	Transmitting	20	40	1	1	0	365	0
Ground; fixed: (G_F)	Transmitting and access	11	31	1	1	0	365	8

5.8.2 Military and civilian avionics

Mission profiles described hereinafter correspond to the MIL-HDBK-217F "Airborne; Inhabited; Cargo" environment.

Several working phases are considered.

- The working rate considers only one internal working temperature for the equipment, and takes into account the total hours of annual working.

- Three phases of thermal cycling are taken in account:

. Phase 1: first daily switch on;

- . Phase 2: switch-off between two flights, while air conditioning of the plane is working;
- . Phase 3: plane on the ground, not working.

For more complex mission profiles, all the temperature's gradient seen by components during the various different working and storage cycles have to be taken into account.

Table 10 – Mission profiles for military and civil avionics

Mission profile phases		Annual working rate for the equipment			First daily switching on		Switch-off Between two fights		Ground Non-working	
Plane types	$(t_{ac})_1$ °C	τ_1	τ_{on}	τ_{off}	n_1 cycles/year	ΔT_1 °C/cycle	n_2 cycles/year	ΔT_2 °C/cycle	n_3 cycles/year	ΔT_3 °C/cycle
A340	40	0.61	0.61	0.39	330	$\frac{\Delta T_j}{3} + 30$	330	$\frac{\Delta T_j}{3} + 15$	35	10
A330	40	0.54	0.54	0.46	330	$\frac{\Delta T_j}{3} + 30$	660	$\frac{\Delta T_j}{3} + 15$	35	10
A320	40	0.58	0.58	0.42	330	$\frac{\Delta T_j}{3} + 30$	1155	$\frac{\Delta T_j}{3} + 15$	35	10
Regional plane	40	0.61	0.61	0.39	330	$\frac{\Delta T_j}{3} + 30$	2970	$\frac{\Delta T_j}{3} + 15$	35	10
Business plane	40	0.22	0.22	0.78	300	$\frac{\Delta T_j}{3} + 30$	300	$\frac{\Delta T_j}{3} + 30$	65	10
Weapons plane	60	0.05	0.05	0.95	200	$\frac{\Delta T_j}{3} + 50$	0	0	165	10
Military cargo	50	0.05	0.05	0.95	250	$\frac{\Delta T_j}{3} + 40$	0	0	115	10
Patroller	50	0.09	0.09	0.91	300	$\frac{\Delta T_j}{3} + 40$	0	0	65	10
Helicopter	50	0.06	0.06	0.94	300	$\frac{\Delta T_j}{3} + 40$	0	0	65	10

5.8.3 Automotive

Mission profiles described hereinafter correspond to the MIL-HDBK-217F "Ground; mobile" environment.

Several working phases are considered..

- The working rates consider three different internal working temperatures for the equipment, and take into account the annual working hours for each of these temperatures. The overall working time is estimated to be 500 h.
- Two thermal cycling are considered:
Phase 1: 2 night starts;
Phase 2: 4 day light starts.
- Phase 3: non-used vehicle, dormant mode 30 days per year.

Table 11 – Mission profiles for automotive

Mission profile phases	Temp. 1		Temp. 2		Temp. 3		Ratios on/off		2 night starts		4 day light starts		Non used vehicle	
Application types	$(t_{ac})_1$ °C	τ_1	$(t_{ac})_2$ °C	τ_2	$(t_{ac})_3$ °C	τ_3	τ_{on}	τ_{off}	n_1 cycles/year	ΔT_1 °C/cycle	n_2 cycles/year	ΔT_2 °C/cycle	n_3 cycles/year	ΔT_3 °C/cycle
Motor control	32	0.02 0	60	0.01 5	85	0.02 3	0.05 8	0.94 2	670	$\frac{\Delta T_j}{3} + 55$	1340	$\frac{\Delta T_j}{3} + 45$	30	10
Passenger compartment	27	0.00 6	30	0.04 6	85	0.00 6	0.05 8	0.94 2	670	$\frac{\Delta T_j}{3} + 30$	1340	$\frac{\Delta T_j}{3} + 20$	30	10

6 Equipped printed circuit boards and hybrid circuits (IEC 60326)

6.1 Failure rate calculation of an equipped printed circuit board

Equipped board failure rate: $(A+B) \times 10^{-9} / \text{hour}$, with: A = connections and components ; B = board

$$A = \left[\sum \lambda_s + \sum \lambda_f + \left(1 + 3.10^{-3} \times \left[\sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right) \times \sum \lambda_d \right]$$

Surface mounted components + Through hole components + Miscellaneous connections

λ_s : Failure rate of each particular surface mounted component (with its influence factors) expressed in $10^{-9}/\text{hour}^*$.

λ_f : Failure rate of each trough hole component (with its influence factors) expressed in $10^{-9}/\text{hour}^*$.

* If the failure rate is $3.10^{-9} / \text{h}$, take λ_s (or λ_f) =3

Mathematical expression of the Influence factor $(\pi_n)_i$	$n_i \leq 8760$ Cycles/year	$(\pi_n)_i = n_i^{0.76}$
	$n_i > 8760$ Cycles/year	$(\pi_n)_i = 1.7 \times n_i^{0.60}$
n_i : Annual number of cycles with the amplitude ΔT_i		
For an on/off phase	$\Delta T_i = (t_{ae})_i - (t_{ae})_i$	
For a permanent working phase, storage or dormant	ΔT_i =average per cycle of the (t_{ae}) variation, during the i^{th} phase of the mission profile.	

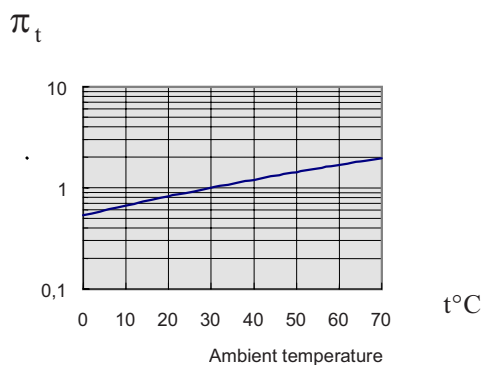
Miscellaneous connections	λ_d FIT
Manual soldering	0.5
Connecting with insulating transfer	0.5
Crimp...	0.3
Wrapped connection	0.01
Pressfit connection	0.006

$(t_{ae})_i$: average external ambient temperature of the equipment, during the i^{th} phase of the mission profile
 $(t_{ae})_i$: average internal ambient temperature, near the components, where the temperature gradient is cancelled.

$(\pi_n)_i$: i^{th} influence factor related to the annual cycle number of thermal variation, seen by the board with an amplitude of ΔT_i .

ΔT_i : i^{th} thermal variation amplitude of the mission profile.

$$B = 5.10^{-3} \cdot \pi_t \cdot \pi_c \left[N_t \sqrt{1 + \frac{N_t}{S}} + N_p \cdot \frac{1 + 0.1\sqrt{S}}{3} \cdot \pi_L \right] \times \left(1 + 3.10^{-3} \times \left[\sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right)$$



Mathematical expression for π_t

$$\pi_t = e^{1740 \left(\frac{1}{303} - \frac{1}{273 + t_A} \right)} \text{ with } t_A : \text{ambient temperature}$$

Number of layers influence	
Number of layers	π_C
≤ 2	1
> 2	$0.7\sqrt{\text{number of layers}}$

N_t = Total number of holes
(for through holes components and vias)

S = Board surface (cm^2)

N_p = number of tracks

Default value:

$$N_p = \frac{(\text{total number of connections})}{2} = \frac{\sum N_s + \sum N_f}{2}$$

N_s : number of connections for each particular surface mounted component.

N_f : number of connections for each particular through hole component.

Influence of the track width						
Predominant track width (mm)	0.56	0.35	0.23	0.15	0.10	0.08
π_L	1	2	3	4	5	6

6.2 Hybrid circuits

Hybrid circuit failure rate: $(A + B) \times 10^{-9} / \text{hour}$
components

A = Add on components and packages; B = substrate and deposited

$$A = \left[\sum \lambda_s + \left(0.023 \times (\alpha_s - \alpha_c)^{1.68} \right) \times \left(2.7 \times 10^{-3} \times \left[\sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right) \times 0.2 \times \pi_p \times D^{1.57} \right]$$

Add on components + package

λ_s : Failure rate of each add on component expressed in $10^{-9} / \text{hour}$, (with its influence factors)*
* If the failure rate is $3.10^{-9} / h$, take $\lambda_s = 3$

D: hybrid circuit diagonal, or distance between farrest pins, in millimeters.

α_s	Linear thermal expansion coefficient of the mounting substrate of the hybrid in ppm/°C
α_c	Linear thermal expansion coefficient of the hybrid substrate in ppm/°C

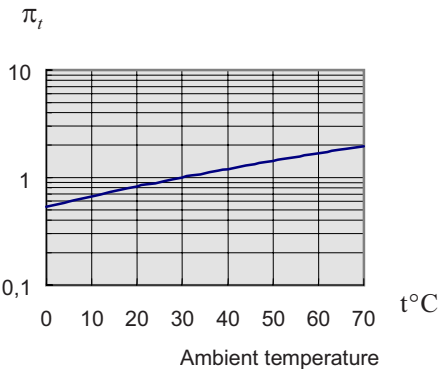
Connecting type	π_p
Single in line	1
Double in line	2
Peripheral	4

Mathematical expression of the Influence factor $(\pi_n)_i$	$n_i \leq 8760$ Cycles/year	$(\pi_n)_i = n_i^{0.76}$
	$n_i > 8760$ Cycles/year	$(\pi_n)_i = 1.7 \times n_i^{0.60}$
n_i : Annual number of cycles with the amplitude ΔT_i		
For an on/off phase	$\Delta T_i = (t_{ac})_i - (t_{ae})_i$	
For a permanent working phase, storage or dormant	ΔT_i = average per cycle of the (t_{ae}) variation, during the i^{th} phase of the mission profile.	

$$B = \left\{ 5 \times 10^{-3} \pi_c \left[N_i \sqrt{1 + \frac{N_i}{S}} + N_p \frac{1 + 0.1\sqrt{S}}{3} \pi_L + 0.8 N_x \right] + \pi_i \left[\sum (0.01 R_e + 0.04 R_m) \pi_i + 0.1 C \right] \right\} \times \left(1 + 2.7 \times 10^{-3} \times \left[\sum_{i=1}^j (\pi_n)_i \times (\Delta T_i)^{0.68} \right] \right)$$

interconnections, crossovers

deposited components



C : Number of deposited capacitors
R_e : Number of thick film resistors having a same factor π_i *
R_m : Number of thin film resistors having a same factor π_i *

Precision factor *	π_i
Tolerance > 5%	1
Tolerance from 1 to 5%	1.5
Tolerance < 1%	2

*: Count apart resistors according to π_i

N_p = number of tracks
Default value:
$$= \frac{(\text{number of components connections})}{2}$$

N_x : number of crossover

Mathematical expression for π_t
$\pi_t = e^{1740 \left(\frac{1}{303} - \frac{1}{273 + t_A} \right)}$ with t_A : ambient temperature

Number of layers influence	
Number of layers	π_c
≤ 2	1
> 2	$0.7 \sqrt{(\text{number of layers})}$

S = Substrate surface (cm^2)
 N_t = number of holes for interconnections

Tracks width influence						
Predominant width (mm)	0,56	0,35	0,23	0,15	0,10	0,08
π_L	1	2	3	4	5	6

7 Integrated circuits

7.1 Validity domain

The end of life period of an integrated circuit is supposed to appear far beyond the utilization period of the equipment. This assumption has to be assessed by a preliminary qualification.

The main failure mechanisms to assess are following:

- For silicon technologies:
 - electromigration;
 - oxides ageing;
 - hot electrons;
 - charge gain and charge (for the write – erase cycles of the various programmable memories).
- For GaAs technologies:
 - gate sink;
 - Ohmic contact degradation;
 - gate and drain lagging;
 - electromigration.
- Packages:
 - thermal fatigue;
 - purple plague.

Estimated failure rates are valid, only if the coldest part temperature of the considered card is over the dew point temperature.

The model does not include the failure rate due to soft errors¹ provoked by the creation of electron-hole pair, on the passage of alpha particle emitted by the package materials. This failure rate due to soft errors may be of the same order of magnitude as the intrinsic failure rate, especially for dynamic memories.

For interface circuits, the models include a failure rate considered to be constant, due to external electrical influences. This failure rate depends on the electrical environment of the equipment, given that the equipment does have primary or secondary protections, depending on the state of the art of the period observed. (For the purposes of this report, interface circuits are taken to be circuits or devices connecting the equipment to the outside environment.)

7.2 Junction temperature evaluation of an integrated circuit

By default, the following simplified method will be used:

7.2.1 The junction temperature is given according to the average power dissipated in the integrated circuit by one of the following equations:

$$\begin{aligned} t_j &= t_a + P \times R_{ja} \\ t_j &= t_c + P \times R_{jc} \end{aligned}$$

in which

- t_a is the ambient temperature around the integrated circuit (°C);
- t_c is the case temperature of the integrated circuit (°C);
- t_j is the junction temperature of the integrated circuit (°C);
- R_{ja} is the junction-ambient thermal resistance of the integrated circuit (°C/W);
- R_{jc} is the junction-case thermal resistance of the integrated circuit (°C/W);
- P is the average power dissipated by the integrated circuit (Watt).

¹ When the function is fully retrievable without outside intervention.